

Inter-linked Platform for Campus Placement in Higher Educational Institutions of India

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Abstract: *This research paper introduces an Inter-linked Campus Placement Platform (ICPP) designed to unify and streamline campus placement activities across Higher Educational Institutions (HEIs) in India. The platform addresses fragmentation by connecting students, placement officers, and recruiters via a cloud-based, AI-powered system that integrates eligibility filtering, intelligent candidate-job matching, and analytics-driven reporting. Utilizing RESTful APIs and federated data architecture, the platform enhances collaboration while ensuring data security and privacy compliance under the Digital Personal Data Protection (DPDP) Act, 2023. Results from a multi-campus pilot across MIT ADT University, Symbiosis Institute of Technology, and DY Patil College demonstrate **42% scheduling efficiency gains, 28% recruiter satisfaction improvement, and 33% faster shortlisting cycles**. The study highlights the architecture, matching algorithms, performance evaluation, and roadmap for nationwide adoption.*

Keywords: Campus Placement, Inter-institutional Integration, Machine Learning, Higher Education, Cloud Computing, Federated System, Data Privacy

